Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!

Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

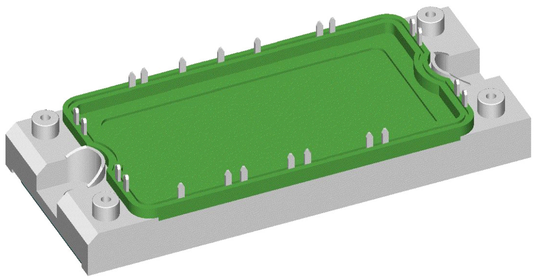
Thyristor Module

3~ Rectifier		Brake Chopper	
V_{RRM} =	1600	V_{CES} =	1200
I_{DAV} =	150	I_{C25} =	120
I_{FSM} =	700	$V_{CE(sat)}$ =	1,8

3~ Rectifier Bridge, half-controlled (high-side) + Brake Unit + NTC

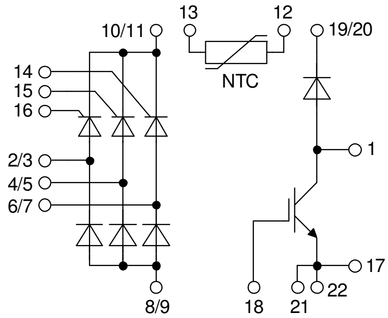
Part number

VVZB135-16ioXT



Backside: isolated

E72873



Features / Advantages:

- Package with DCB ceramic
- Improved temperature and power cycling
- Planar passivated chips
- Very low forward voltage drop
- Very low leakage current
- NTC

Applications:

- 3~ Rectifier with brake unit for drive inverters

Package: E2-Pack

- Isolation Voltage: 3600 V~
- Industry standard outline
- RoHS compliant
- Soldering pins for PCB mounting
- Height: 17 mm
- Base plate: DCB ceramic
- Reduced weight
- Advanced power cycling

Rectifier				Ratings			
Symbol	**Definition**	**Conditions**		**min.**	**typ.**	**max.**	**Unit**
$V_{RSM/DSM}$	*max. non-repetitive reverse/forward blocking voltage*		T_{VJ} = 25°C			1700	V
$V_{RRM/DRM}$	*max. repetitive reverse/forward blocking voltage*		T_{VJ} = 25°C			1600	V
$I_{R/D}$	*reverse current, drain current*	$V_{R/D}$ = 1600 V	T_{VJ} = 25°C			100	µA
		$V_{R/D}$ = 1600 V	T_{VJ} = 150°C			20	mA
V_T	*forward voltage drop*	I_T = 50 A	T_{VJ} = 25°C			1,32	V
		I_T = 150 A				1,92	V
		I_T = 50 A	T_{VJ} = 125°C			1,26	V
		I_T = 150 A				1,96	V
I_{DAV}	*bridge output current*	T_C = 85°C rectangular d = ⅓	T_{VJ} = 150°C			150	A
V_{T0}	*threshold voltage*	*for power loss calculation only*	T_{VJ} = 150°C			0,88	V
r_T	*slope resistance*					7,3	mΩ
R_{thJC}	*thermal resistance junction to case*					0,65	K/W
R_{thCH}	*thermal resistance case to heatsink*				0,10		K/W
P_{tot}	*total power dissipation*		T_C = 25°C			190	W
I_{TSM}	*max. forward surge current*	t = 10 ms; (50 Hz), sine	T_{VJ} = 45°C			700	A
		t = 8,3 ms; (60 Hz), sine	V_R = 0 V			755	A
		t = 10 ms; (50 Hz), sine	T_{VJ} = 150°C			595	A
		t = 8,3 ms; (60 Hz), sine	V_R = 0 V			645	A
I^2t	*value for fusing*	t = 10 ms; (50 Hz), sine	T_{VJ} = 45°C			2,45	kA²s
		t = 8,3 ms; (60 Hz), sine	V_R = 0 V			2,37	kA²s
		t = 10 ms; (50 Hz), sine	T_{VJ} = 150°C			1,77	kA²s
		t = 8,3 ms; (60 Hz), sine	V_R = 0 V			1,73	kA²s
C_J	*junction capacitance*	V_R = 400 V f = 1 MHz	T_{VJ} = 25°C		32		pF
P_{GM}	*max. gate power dissipation*	t_P = 30 µs	T_C = 150°C			10	W
		t_P = 300 µs				5	W
P_{GAV}	*average gate power dissipation*					0,5	W
$(di/dt)_{cr}$	*critical rate of rise of current*	T_{VJ} = 150°C; f = 50 Hz t_P = 200 µs; di_G/dt = 0,45 A/µs;	repetitive, I_T = 150 A			150	A/µs
		I_G = 0,45 A; V = ⅔ V_{DRM}	non-repet., I_T = 50 A			500	A/µs
$(dv/dt)_{cr}$	*critical rate of rise of voltage*	V = ⅔ V_{DRM} R_{GK} = ∞; method 1 (linear voltage rise)	T_{VJ} = 150°C			1000	V/µs
V_{GT}	*gate trigger voltage*	V_D = 6 V	T_{VJ} = 25°C			1,4	V
			T_{VJ} = -40°C			1,6	V
I_{GT}	*gate trigger current*	V_D = 6 V	T_{VJ} = 25°C			80	mA
			T_{VJ} = -40°C			200	mA
V_{GD}	*gate non-trigger voltage*	V_D = ⅔ V_{DRM}	T_{VJ} = 150°C			0,2	V
I_{GD}	*gate non-trigger current*					5	mA
I_L	*latching current*	t_p = 10 µs I_G = 0,45 A; di_G/dt = 0,45 A/µs	T_{VJ} = 25°C			450	mA
I_H	*holding current*	V_D = 6 V R_{GK} = ∞	T_{VJ} = 25°C			100	mA
t_{gd}	*gate controlled delay time*	V_D = ½ V_{DRM} I_G = 0,45 A; di_G/dt = 0,45 A/µs	T_{VJ} = 25°C			2	µs
t_q	*turn-off time*	V_R = 100 V; I_T = 50 A; V = ⅔ V_{DRM} di/dt = 10 A/µs dv/dt = 20 V/µs t_p = 200 µs	T_{VJ} = 125 °C		150		µs

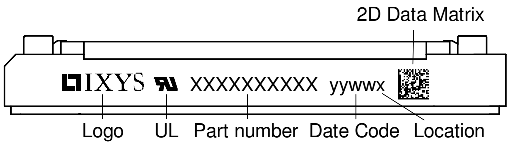
Brake IGBT

Symbol	Definition	Conditions		min.	typ.	max.	Unit
V_{CES}	*collector emitter voltage*		T_{VJ} = 25°C			1200	V
V_{GES}	*max. DC gate voltage*					±20	V
V_{GEM}	*max. transient gate emitter voltage*					±30	V
I_{C25}	*collector current*		T_C = 25°C			120	A
I_{C80}			T_C = 80°C			84	A
P_{tot}	*total power dissipation*		T_C = 25°C			390	W
$V_{CE(sat)}$	*collector emitter saturation voltage*	I_C = 75 A; V_{GE} = 15 V	T_{VJ} = 25°C		1,8	2,1	V
			T_{VJ} = 125°C		2,1		V
$V_{GE(th)}$	*gate emitter threshold voltage*	I_C = 3 mA; V_{GE} = V_{CE}	T_{VJ} = 25°C	5,5	6,0	6,5	V
I_{CES}	*collector emitter leakage current*	V_{CE} = V_{CES}; V_{GE} = 0 V	T_{VJ} = 25°C			0,2	mA
			T_{VJ} = 125°C		0,6		mA
I_{GES}	*gate emitter leakage current*	V_{GE} = ±20 V				500	nA
$Q_{G(on)}$	*total gate charge*	V_{CE} = 600 V; V_{GE} = 15 V; I_C = 75 A			230		nC
$t_{d(on)}$	*turn-on delay time*	inductive load V_{CE} = 600 V; I_C = 75 A V_{GE} = ±15 V; R_G = 10 Ω	T_{VJ} = 125°C		70		ns
t_r	*current rise time*				40		ns
$t_{d(off)}$	*turn-off delay time*				250		ns
t_f	*current fall time*				100		ns
E_{on}	*turn-on energy per pulse*				6,8		mJ
E_{off}	*turn-off energy per pulse*				8,3		mJ
RBSOA	*reverse bias safe operating area*	V_{GE} = ±15 V; R_G = 10 Ω	T_{VJ} = 125°C				
I_{CM}		V_{CEK} = 1200 V				225	A
SCSOA	*short circuit safe operating area*	V_{CEK} = 1200 V					
t_{SC}	*short circuit duration*	V_{CE} = 900 V; V_{GE} = ±15 V	T_{VJ} = 125°C			10	µs
I_{SC}	*short circuit current*	R_G = 10 Ω; non-repetitive			300		A
R_{thJC}	*thermal resistance junction to case*					0,32	K/W
R_{thCH}	*thermal resistance case to heatsink*				0,15		K/W

Brake Diode

Symbol	Definition	Conditions		min.	typ.	max.	Unit
V_{RRM}	*max. repetitive reverse voltage*		T_{VJ} = 25°C			1200	V
I_{F25}	*forward current*		T_C = 25°C			48	A
I_{F80}			T_C = 80°C			32	A
V_F	*forward voltage*	I_F = 30 A	T_{VJ} = 25°C			2,75	V
			T_{VJ} = 125°C		1,99		V
I_R	*reverse current*	V_R = V_{RRM}	T_{VJ} = 25°C			0,25	mA
			T_{VJ} = 125°C			1	mA
Q_{rr}	*reverse recovery charge*	V_R = 600 V $-di_F/dt$ = 400 A/µs I_F = 30 A	T_{VJ} = 125°C		1,8		µC
I_{RM}	*max. reverse recovery current*				23		A
t_{rr}	*reverse recovery time*				150		ns
R_{thJC}	*thermal resistance junction to case*					0,9	K/W
R_{thCH}	*thermal resistance case to heatsink*				0,3		K/W

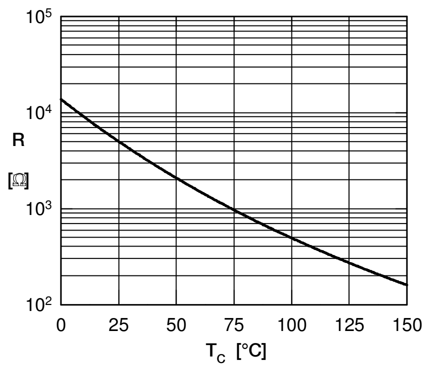
Package E2-Pack				Ratings			
Symbol	**Definition**	**Conditions**		**min.**	**typ.**	**max.**	**Unit**
I_{RMS}	*RMS current*	per terminal				200	A
T_{VJ}	*virtual junction temperature*			-40		150	°C
T_{op}	*operation temperature*			-40		125	°C
T_{stg}	*storage temperature*			-40		125	°C
Weight					176		g
M_D	*mounting torque*			3		6	Nm
$d_{Spp/App}$	*creepage distance on surface | striking distance through air*		*terminal to terminal*	6,0			mm
$d_{Spb/Apb}$			*terminal to backside*	12,0			mm
V_{ISOL}	*isolation voltage*	t = 1 second	50/60 Hz, RMS; I_{ISOL} ≤ 1 mA	3600			V
		t = 1 minute		3000			V



Ordering	Ordering Number	Marking on Product	Delivery Mode	Quantity	Code No.
Standard	VVZB135-16ioXT	VVZB135-16ioXT	Box	6	510134

Temperature Sensor NTC

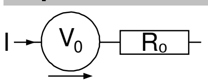
Symbol	Definition	Conditions	min.	typ.	max.	Unit
R_{25}	*resistance*	T_{VJ} = 25°	4,75	5	5,25	kΩ
$B_{25/50}$	*temperature coefficient*			3375		K



Typ. NTC resistance vs. temperature

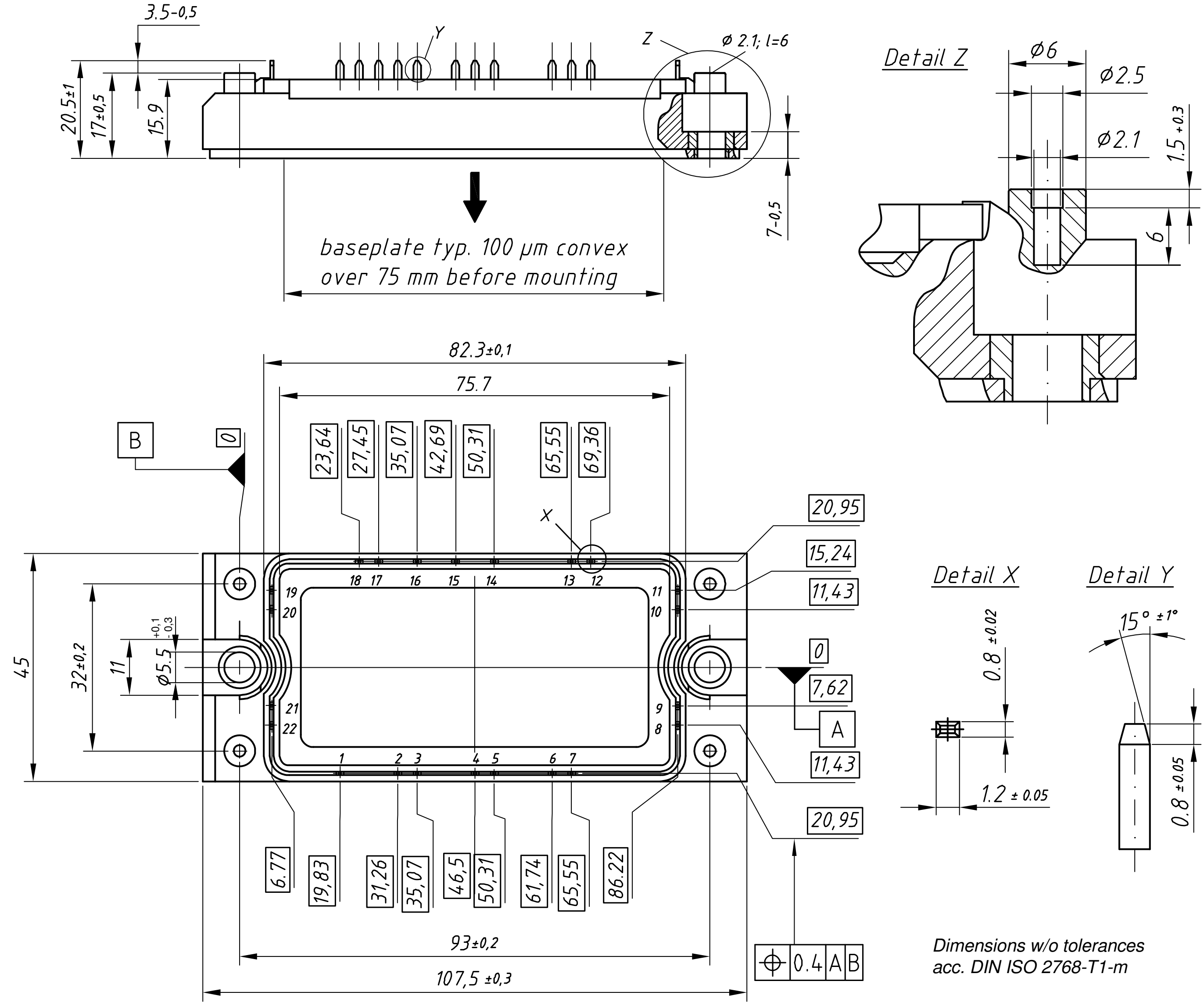
Equivalent Circuits for Simulation

** on die level* T_{VJ} = 150 °C

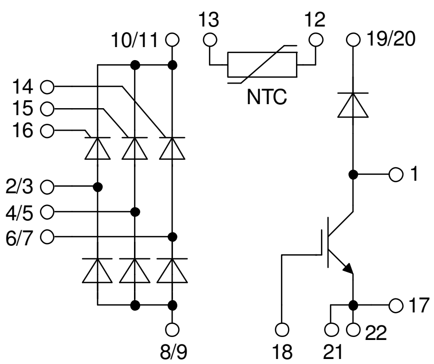


		Thyristor	Brake IGBT	Brake Diode	
$V_{0\ max}$	*threshold voltage*	0,88	1,1	1,31	V
$R_{0\ max}$	*slope resistance **	4,1	17,9	8	mΩ

Outlines E2-Pack



Dimensions w/o tolerances acc. DIN ISO 2768-T1-m



Thyristor

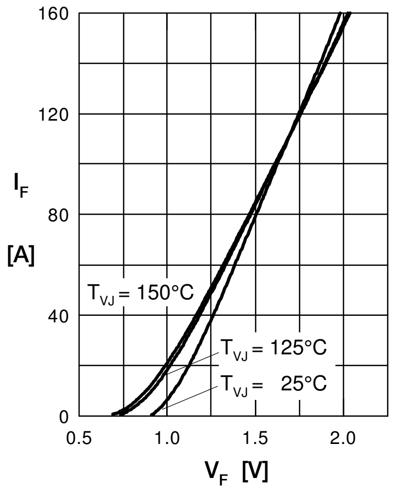


Fig. 1 Forward current vs. voltage drop per thyristor

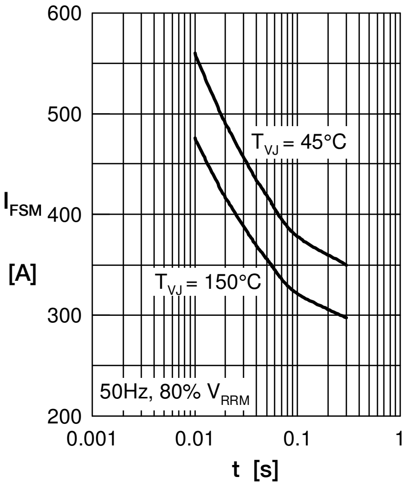


Fig. 2 Surge overload current vs. time per thyristor

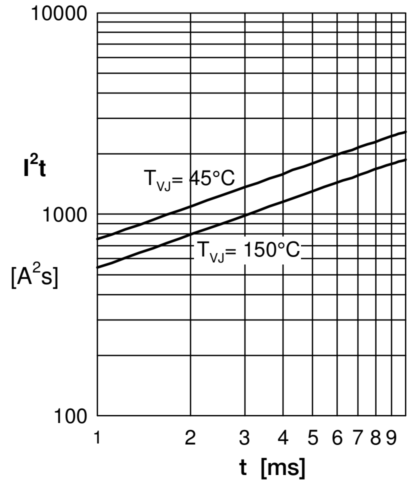


Fig. 3 I^2t vs. time per thyristor

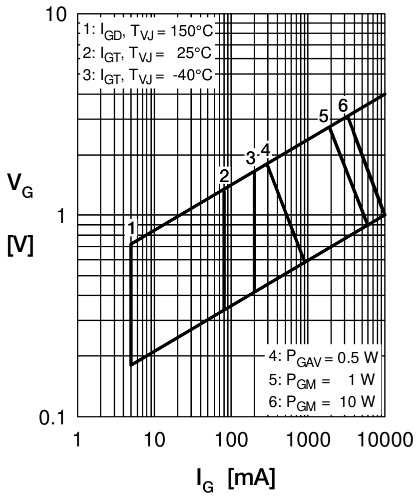


Fig. 4 Gate trigger characteristics

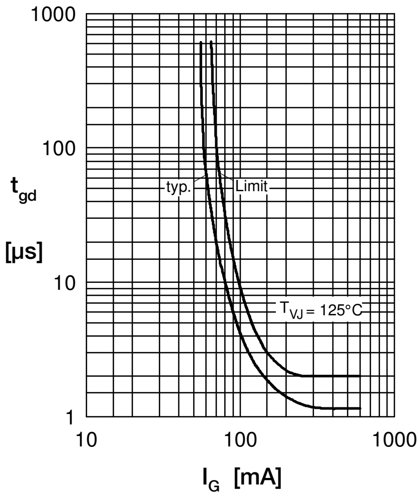


Fig. 5 Gate controlled delay time

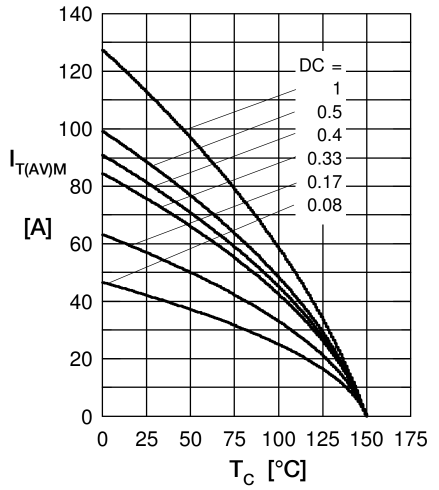


Fig. 5 Max. forward current vs. case temperature per thyristor

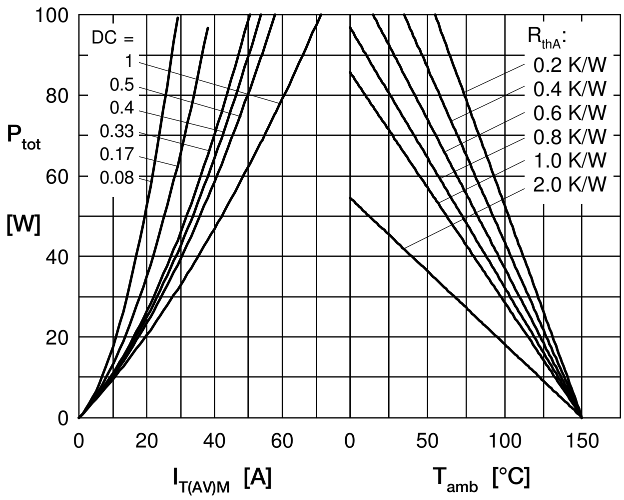


Fig. 4 Power dissipation vs. forward current and ambient temperature per thyristor

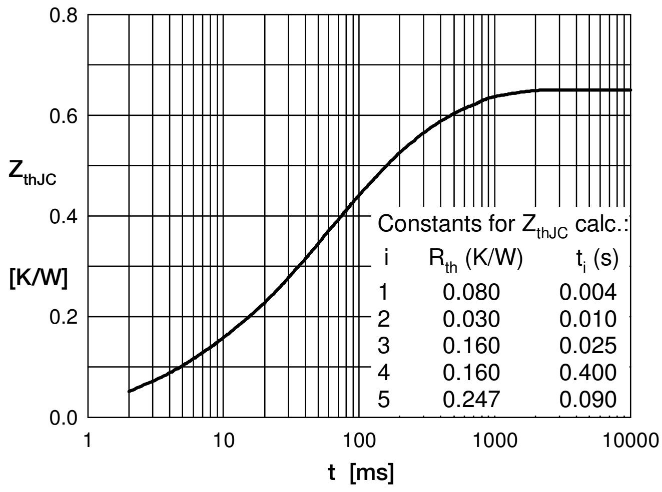


Fig. 6 Transient thermal impedance junction to case vs. time per thyristor

Brake IGBT

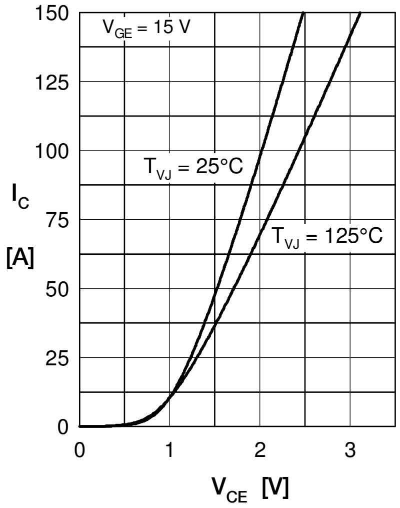


Fig. 1 Typ. output characteristics

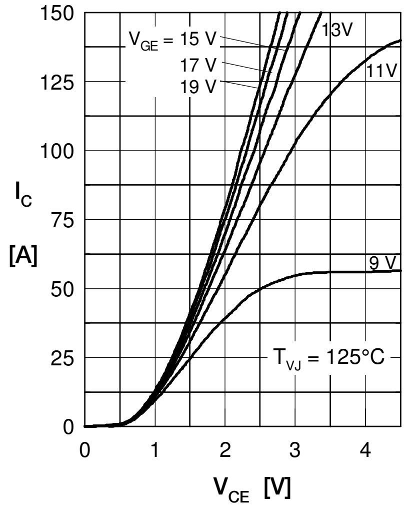


Fig. 2 Typ. output characteristics

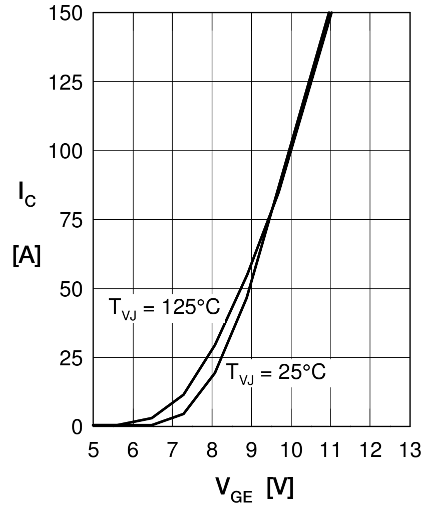


Fig. 3 Typ. tranfer characteristics

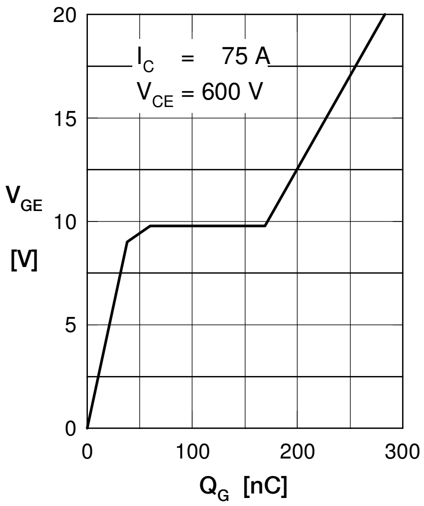


Fig. 4 Typ. turn-on gate charge

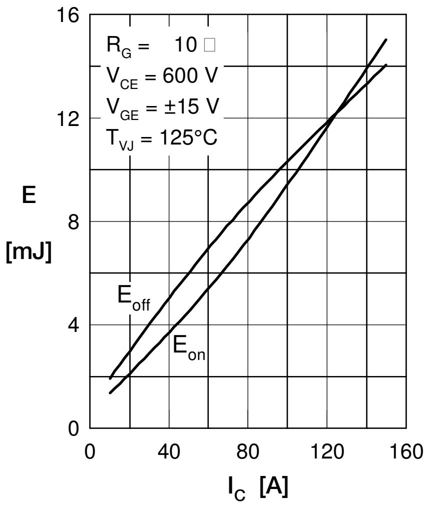


Fig. 5 Typ. switching energy versus collector current

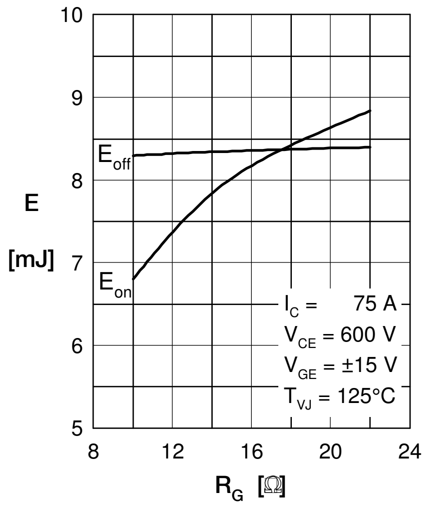


Fig. 6 Typ. switching energy versus gate resistance

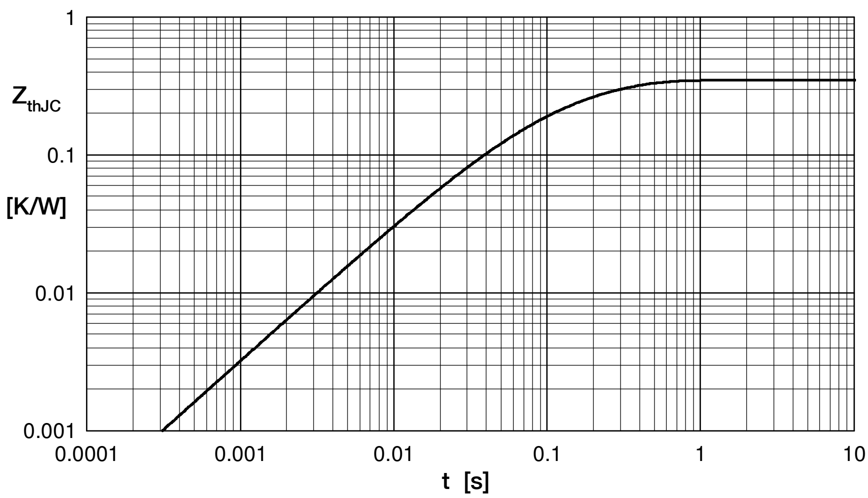


Fig. 7 Typ. transient thermal impedance junction to case

Brake Diode

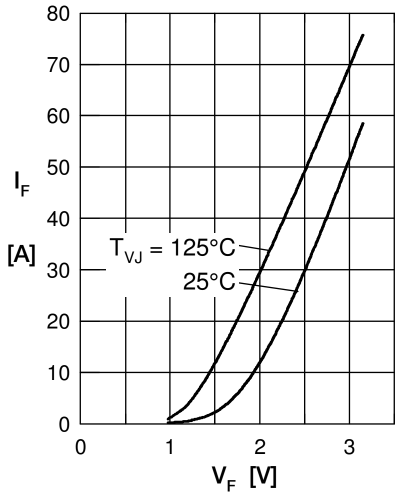


Fig. 1 Forward current I_F vs. V_F

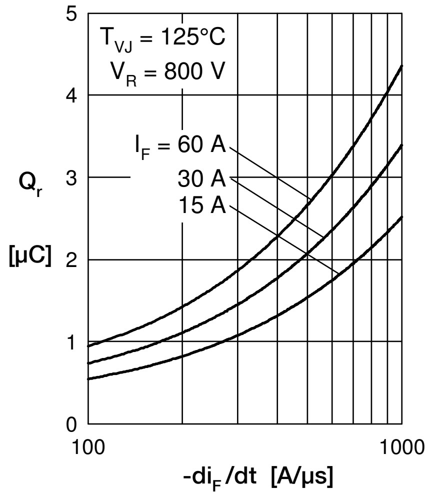


Fig. 2 Typ. reverse recovery charge Q_r versus $-di_F/dt$

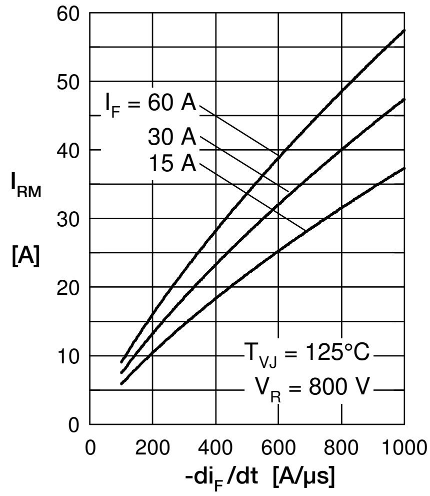


Fig. 3 Typ. peak reverse current I_{RM} versus $-di_F/dt$

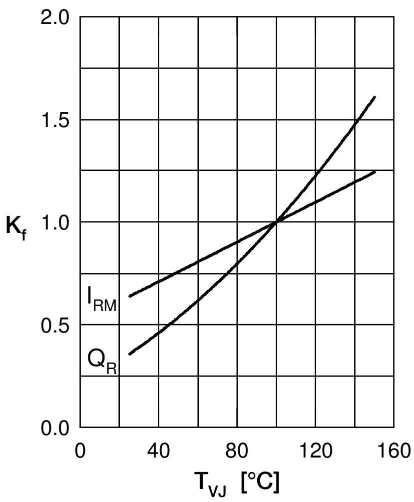


Fig. 4 Dynamic parameters Q_r, I_{RM} versus T_{VJ}

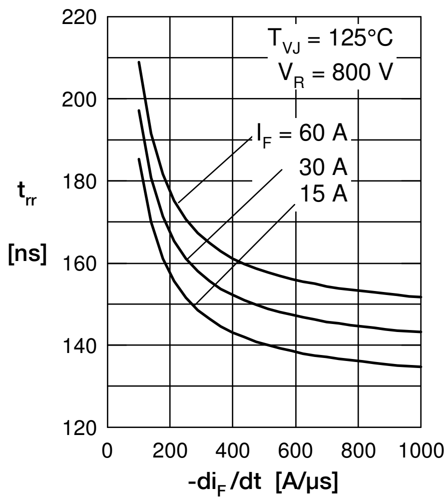


Fig. 5 Typ. recovery time t_{rr} versus $-di_F/dt$

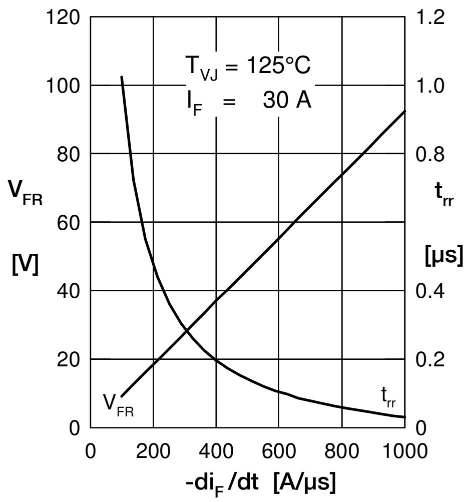


Fig. 6 Typ. peak forward voltage V_{FR} and t_{fr} versus di_F/dt

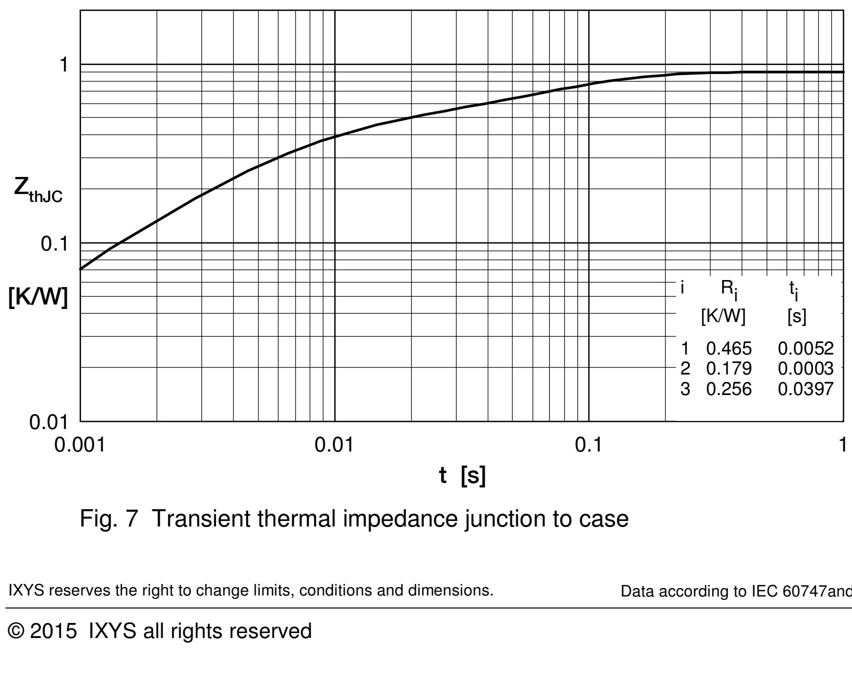


Fig. 7 Transient thermal impedance junction to case